ASSOCIATION CONNECTING ELECTROMICS INDUSTRIES® international and	<b>position De</b> 5. IPC, Bannockt Pan-American co	c <b>laration</b> ourn, Illinois. A opyright conver	ll rights reserved untions.	under both	This docume level parts, t	ent is a declaration he declaration er	on of the substar	ces within the n ower level mater	nanufacturer	listed item. Note h the manufactur	if the item is an as er has engineering	ssembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form 7   http://www.ipc.org/IPC-175x Distrib				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater				ous Materials	ials and Mfg Information			
upplier Information													
Company name* Co			Company unique ID			Unique ID Authority				Response Date*			
onsemi										2023-06-08			
Contact Name Title - Co			le - Contact			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Prod			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative* Title -			itle - Representative			Phone - Representative*			E	Email - Representative*			
Product-Env-Stewards Pro			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Item	Mfr Item Number Mfr Item Nat		Mfr Item Name BR TS6P GPPN 20A 200V		Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
	DFB202					2023-06-08		TSCBE		7671.0	mg	Each	
Ianufacturing Proccess Inform	nation		-										
Terminal Plating / Grid Array	Terminal Plating / Grid Array Material Terminal Base A		Alloy	J-STD-020 MSL Rating		Peak Process Body Temperature		ature Max Tim	ne at Peak Te	mperature Nur	nber of Reflow Cy	cles	
Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30		seconds 3				
omments													
or more information regarding mater	ial composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).							
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die Attach Solder	200.0	mg	Supplier	Silver (Ag)	7440-22-4		5	mg
			А	Lead (Pb)	7439-92-1	7a	185	mg
			Supplier	Tin (Sn)	7440-31-5		10	mg
Jumper	60.4	mg	Supplier	Iron (Fe)	7439-89-6		0.05	mg
			Supplier	Copper (Cu)	7440-50-8		60.34	mg
			Supplier	Phosphorus (P)	7723-14-0		0.01	mg
Lead Frame	2315.0	mg	Supplier	Iron (Fe)	7439-89-6		1.852	mg
			Supplier	Copper (Cu)	7440-50-8		2312.6851	mg
			Supplier	Phosphorus (P)	7723-14-0		0.463	mg
Mold Compound-Black	4807.0	mg	В	Brominated Bisphenol A Diglycidyl Ether	40039-93-8		96.14	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		721.05	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		96.14	mg
			Supplier	Carbon Black (C)	1333-86-4		48.07	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		480.7	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		3364.8999	mg
Plating	248.6	mg	Supplier	Tin (Sn)	7440-31-5		248.6	mg
Silicon Dice	40.0	mg	Supplier	Silicon (Si)	7440-21-3		39.992	mg
			В	Nickel (Ni)	7440-02-0		0.004	mg
			Supplier	Gold (Au)	7440-57-5		0.004	mg